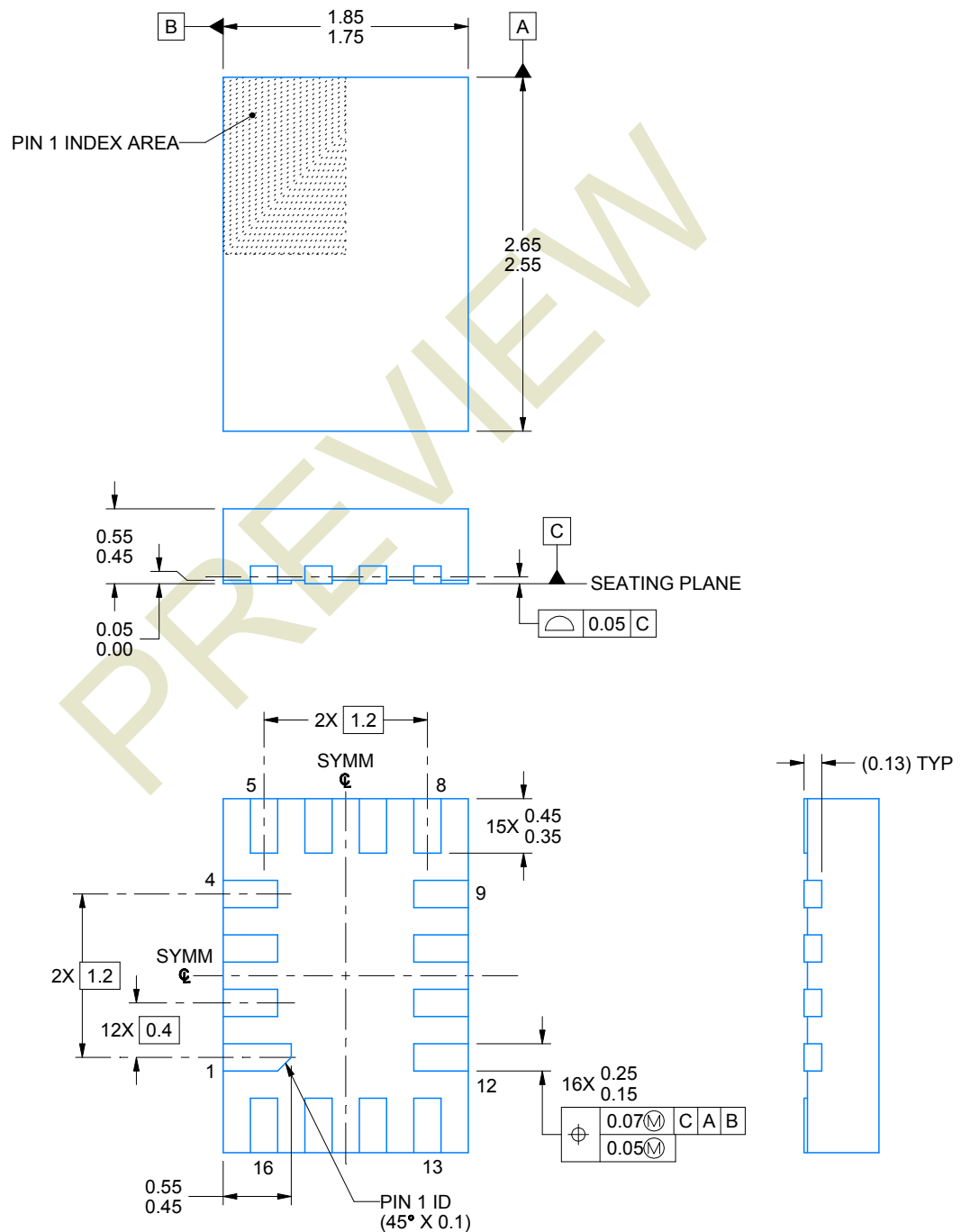
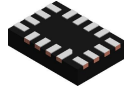


DATA BOOK
PACKAGE OUTLINE

PREVIEW

DRAFTER:	K. SINCERBOX	DATE:	2019	DIMENSIONS IN MILLIMETERS	
DESIGNER:		DATE:		 TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS CODE IDENTITY NUMBER 01295 ePOD, RSV0016A / UQFN, 16 PIN, 0.4 MM PITCH	
CHECKER:	K. SINCERBOX	DATE:	2019		
ENGINEER:	A. TORMA	DATE:	2019		
APPROVED:	D. CHIN & D. MILO	DATE:	2019		
RELEASED:	K. SINCERBOX	DATE:	2019		
TEMPLATE INFO:	EDGE# 4218519	DATE:	04/07/2016	SCALE NTS	SIZE A
				4220314	REV A
					PAGE 1 OF 5



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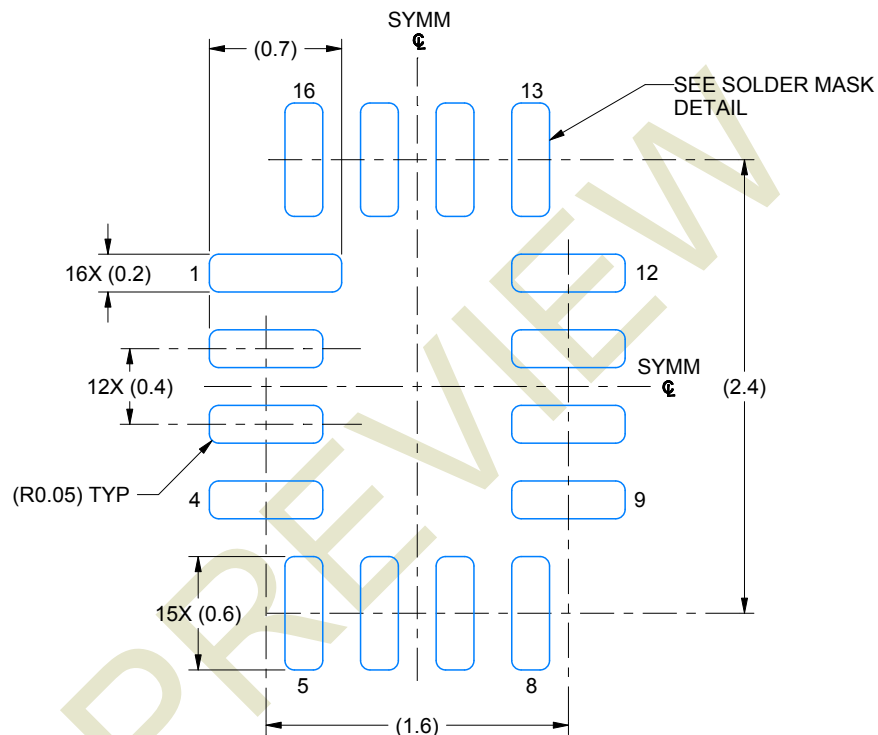
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

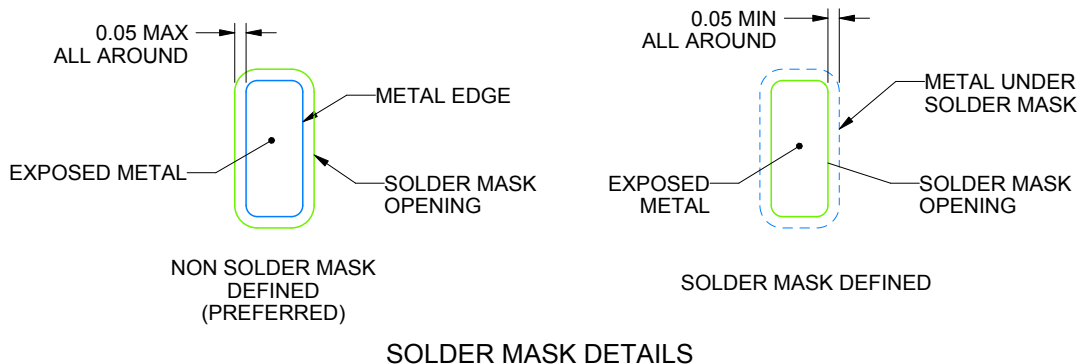
RSV0016A

VQFN - 0.55 mm max height

ULTRA THIN QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 25X



4220314/A 03/2019

NOTES: (continued)

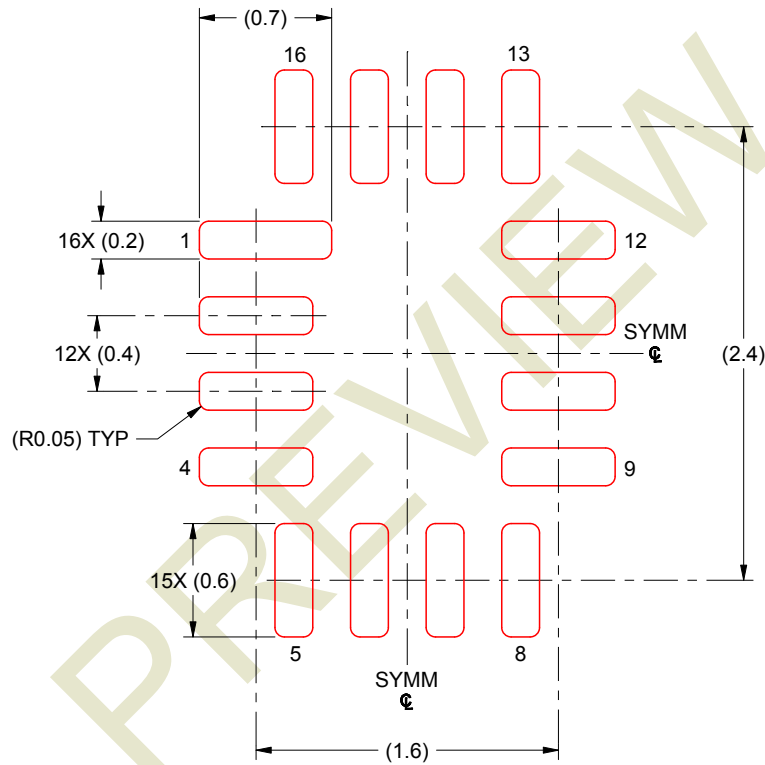
3. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

RSV0016A

VQFN - 0.55 mm max height

ULTRA THIN QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 25X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2180077	2019	A. TORMA / K. SINCERBOX

PREVIEW